

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Complete Listing of Claims:

Claims 1. – 8. (Canceled)

9. (Currently Amended.) An electrically conductive circuit, comprising:
a dielectric substrate having opposing first and second sides;
a first copper foil layer laminated ~~to a~~ to said first side of said dielectric substrate ~~thereof~~, said copper foil coated with a laser ablation inhibiting layer having an average reflectivity value of at least 40 that is effective to provide a lamination peel strength to FR-4 of at least 4.5 pounds per inch;

said dielectric layer having a via extending therethrough and terminating at an interface between said dielectric layer and said first copper foil layer wherein said laser ablation inhibiting layer is effective to prevent said via from extending through said first copper foil.

10. (Original) The electrically conductive circuit of claim 9 wherein the average reflectivity value of said laser ablation inhibiting layer is between 50 and 90.

11. (Original) The electrically conductive circuit of claim 10 wherein said laser ablation inhibiting layer comprises nodules having an average height of from 0.3 micron to 1.0 micron.

12. (Original) The copper foil of claim 11 wherein said laser ablation inhibiting layer is a codeposited mixture of chromium and zinc and their oxides.

13. (Original) The copper foil of claim 11 wherein said laser ablation inhibiting layer is mixture of a metal and a metal oxide and said metal oxide is selected from the group consisting of oxides of chromium, tungsten and molybdenum.

14. (Original) The copper foil of claim 11 wherein said dielectric substrate is selected from the group consisting of glass reinforced epoxy and polyimide.

Claims 15. – 21. (Canceled)